

THERMAL PAD - DT08

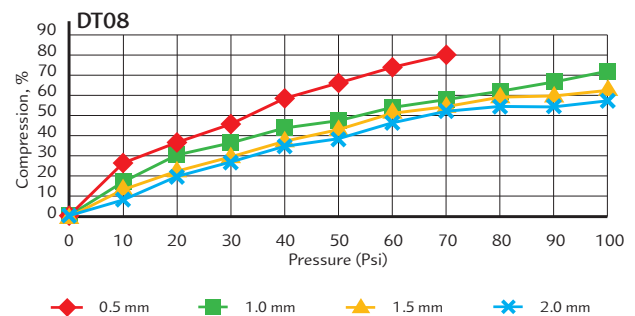
Features

- Thermal conductivity: 0.8 W/mK
- DT08 is available with two different hardnesses: Shore 18 C (DT08/H18) and Shore 35 C (DT08/H35)
- High conformability
- Cost effective solution
- Electrically insulating
- Naturally sticky
- High dielectric breakdown of up to 4.0 kV/mm
- Custom die-cut parts: custom configurations available



Applications

- Between electronic components: semiconductors, ICs, CPUs, MOS and heatsink
- LEDs, LCD TV, telecom devices, wireless hubs, PCs, power supply etc.
- Cooling and thermal modules
- In all applications where a metal housing is used as heatsink.



Part number code (example):

UDT 10/H10 - T 10
 ↳ Thickness: 1.0 mm
 ↳ Hardness: 10 Shore C
 ↳ Thermal Conductivity: 1.0 W/mK
 ↳ UDT: Thermal Pad

TECNITE DT08

Properties	Unit	DT08	Test Method
Composition		Silicone & ceramic filled	
Colour		Grey	
Thickness range	mm	0.5 -12.0	
Hardness	Shore C	18 (DT08/H18) & 35 (DT08-H35)	ASTM D2240
Density	g/ml	2	ASTM D792
Elongation	%	1.35	ASTM D412
Temperature range	°C	-40 to 150	EN344
Breakdown voltage	kV/mm	≥4.0	ASTM D149
Volume impedance	ohm*cm	1.7*10 ¹⁶	ASTM D257
Dielectric constant	@ 1 MHz	4.51	ASTM D150
Weight dampify	%	≥1	@ 150 °C 240H
Thermal conductivity	W/mK	0.8	ASTM E1461
Thermal Resistance @ 40 psi	°C-in ² /W	DT08/H18: 0.968 @ 0.5 mm DT08/H35: 1.483 @ 0.5 mm DT08/H18: 1.713 @ 1.0 mm DT08/H45: 2.324 @ 1.0 mm	
Compliances		UL 94 V-0, RoHS, REACH	
Sheet sizes		Standard: 200*400 mm, 330*330 mm	
Custom configurations		Custom die-cut parts available. Available with acrylic PSA tape for improved application on on or both sides: • 3M Double Coated Tape 9448HK (will make the pad 0.15 mm thicker on both sides) • 3M Transfer Tape 3M467 (will make the pad 0.06 mm thicker on both sides)	

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